

## Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org/IPC-175x>

Form Type\*  
Distribute

**Declaration Class\***  
**Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information**

### Supplier Information

<b>Company Name *</b> Fairchild Semiconductor	<b>Company Unique ID</b> 00-489-5751	<b>Unique ID Authority</b> Dun & Bradstreet	<b>Response Date*</b> Sat, May 26, 2012 05:18 AM
<b>Contact Name *</b> David Lancaster	<b>Title - Contact</b> Product Ecology	<b>Phone - Contact *</b> 801-562-7455	<b>Email - Contact *</b> david.lancaster@fairchildsemi.com
<b>Authorized Representative *</b> David Lancaster	<b>Title - Representative</b> Product Ecology	<b>Phone - Representative *</b> 801-562-7455	<b>Email - Representative *</b> david.lancaster@fairchildsemi.com

Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
SG6858TZ	SG6858TZ	SSOT-6 (AdhesiveAuBW-G)			INTERNAL CEBU	0.017	g	Each

### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Matte Tin (Sn)	CU Alloy	1	260 C	30 seconds	3

\* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
<b>RoHS Directive 2002/95/EC</b>	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>Providing for limitations below, we certify that the Fairchild Semiconductor product(s) list in this document are compliant to directive 2002/95/EC of the European Parliament and of the council on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS directive). Specifically, this product(s) does not contain the substances in the RoHS definition above in concentrations greater than the maximum limit value(a).</p> <p>Fairchild has implemented procedures to ensure our products and the materials in our products conform to regulatory requirements worldwide. Fairchild Semiconductor certifies that the information provided in this document is correct as of the date indicated on this document. However, not all materials in Fairchild's products may have been independently verified or tested with regard to substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>(a) Maximum limit does not apply to applications for which exemptions have been granted by the RoHS directive. Fairchild product may utilize exemption 5 and 7a.</p>		
<b>RoHS Declaration *</b>	<b>4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions</b>	<b>Supplier Acceptance * Accepted</b>
<b>Exemptions:</b> If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.		
Exemption List Version EL-2006/690/EC		
0		

#### Declaration Signature

Supplier Signature	 DAVID LANCASTER - PRODUCT ECOLOGY MANAGER
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**Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name SSOT-6 (AdhesiveAuBW-G)

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.172	Supplier		Silicon	0.172	7440-21-3	9896
Die Attach	Other Organic Materials	0.203	Supplier		Acrylic Resin	0.041	54208-63-8	2336
			Supplier		Silver	0.162	7440-22-4	9320
Encapsulation	Thermoplastics	7.596	Supplier		Carbon Black	0.076	1333-86-4	4367
			Supplier		Epoxy Resin	1.520	29690-82-2	87449
			Supplier		Silica, vitreous	6.000	60676-86-0	345195
Lead Frame	Other Ferrous alloys, non-stainless steels	8.255	Supplier		Copper	8.022	7440-50-8	461554
			Supplier		Iron	0.198	7439-89-6	11391
			Supplier		Phosphorus	0.002	7723-14-0	143
			Supplier		Silver	0.022	7440-22-4	1283
			Supplier		Zinc	0.010	7440-66-6	570
Plating	Other Nonferrous metals & alloys	1.130	Supplier		Tin	1.130	7440-31-5	65012
Wire Bond	Precious metals	0.026	Supplier		Gold	0.026	7440-57-5	1484